

1. COMPANY INFORMATION

Company Name: _____

Date of Submission (DD/MM/YYYY): _____

Headquarters Address: _____

Establishment Date (DD/MM/YY): _____

Line of Business: Semiconductors

Current Full-Time R&D Employees: _____

Annual Revenue (EGP): _____

Annual Exports (EGP): _____

2. FINANCIAL & TAPE-OUT PROPOSAL

Chip / Project Name	Manufacturer / Foundry	Target Tape-Out Date	Reference Prototyping Cost (EGP)
Total Prototyping Budget (for reference only)			EGP _____

3. TECHNICAL PROPOSAL OUTLINE

Please attach a detailed document covering the following points:

Project Team Profile:

Detail full-time R&D team size, specific engineering roles assigned to this project, and technical capabilities.

Product & Architecture Spec:

Define target applications, target industries (e.g., automotive, IoT, consumer tech), commercial deployment roadmap, and technical justifications for prototyping.

Economic Forecasts:

Provide concrete, projected numbers for revenue changes, new hiring, and export volumes resulting from a successful prototype cycle.